

## **REMARKS**

Reconsideration of the above-identified application in view of the foregoing amendments and following remarks is respectfully requested.

### **I. Status of Claims:**

Claims 1, 3-4, 7, and 15-20 are pending. Claim 21 was previously withdrawn from consideration. Applicants reserve the right to pursue the withdrawn claim in a divisional application.

By this paper, claim 1 is amended. Claim 20 has been canceled. New claim 22 has been added. No new matter is introduced into this application by entry of these amendments. Entry is respectfully requested.

### **II. Rejections Under 35 U.S.C. §103:**

Claims 1, 3-4, 7 and 15-20 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Sakashita, et al., U.S. Patent No. 4,742,110 ("Sakashita"). Applicants respectfully traverse this ground of rejection on the basis that the claimed coating composition containing polyimide or polyamide-imide as a binder resin has characteristics different from the prior art polyamide composition containing polyamide as a main component and also containing polymide or polyamide-imide as fillers.

In the Office Action at pages 3-4, the Examiner points out that "With reference to a film forming from said composition, it is noted that Sakashita et al. is drawn to a moldable composition with improved mechanical and thermal characteristics and to a composition which is excellent in molding characteristics. Therefore, it is the position of the examiner that the composition of Sakashita et al. may be molded in any form and shape such as into a film absence clear evidence showing the contrary." Further, the Examiner also states that "Applicants have argued that Sakashita et al. composition includes polyamide as a main component as opposed to

polyimide or polyamide-imide as the binder resin ... This argument is not found persuasive because the reference ... clearly discloses that said composition comprises polyamide-imide (i.e. binder), titanium dioxide (i.e. filler) silane (which treats the titanium dioxide), and polytetrafluoroethylene in overlapping ranges and particle size, wherever applicable (i.e. for titanium oxide particles), as known additives and components to be added to such a polyamide composition. Therefore, the reference clearly teaches the instantly claimed composition, specifically with respect to the components.” Office Action at p. 6.

However, the polyamide composition disclosed in Sakashita includes polyamide as a main component, and is a thermoplastic molding resin having excellent molding characteristics. The polyamide composition, which contains polyamide as a main component, could be molded in any form and shape such as into various molded resin articles, but cannot be used for molding a film formed on the sliding part since the polyamide itself is thermoplastic and has low wear resistant property and low thermal resistant property. Therefore, even if the Sakashita’s composition contains polyimide or polyamide-imide, which has high wear resistant property and high thermal resistant property, this composition is not suitable for molding a film formed on a sliding part as long as it contains polyamide as a main component.

As the Examiner points out, Sakashita describes a polyamide composition with improved mechanical, thermal and strength characteristics. However, this merely indicates that, in the field of molding resins, these characteristics of the Sakashita’s composition are improved as compared with those of the conventional polyamide composition, but does not indicate that these characteristics of the Sakashita’s composition are suitable for a film formed on the sliding part. In the field of films formed on a sliding part, the mechanical, thermal and strength characteristics of Sakashita’s composition would be insufficient.

Furthermore, the claimed coating composition contains polyimide or polyamide-imide as the binder resin. Sakashita, on the other hand, merely discloses that the polyamide composition contains polyimide or polyamide-imide as fillers. In the claim composition, polyimide or polyamide-imide is used as the binder resin for tightly-bonding the film to the sliding part. In contrast, since Sakashita is drawn to a polyamide composition that is suitable for molding resin articles, which are used without being bonded to another member such as sliding part, polyimide or polyamide-imide is used as a filler for improving moldability. Sakashita completely fails to teach or suggest that the composition contains polyimide or polyamide-imide as a binder resin for tightly-bonding the film to the sliding part.

For the above reasons, those skilled in the art would not be motivated to apply the polyamide composition as disclosed in Sakashita to a film formed on the sliding part as recited in independent claim 1. Further, in the claimed composition, the titanium oxide powder having an average primary particle diameter of 1  $\mu\text{m}$  or less has excellent dispersability in the binder resin, which prevents the solid lubricant from dropping out of the film. See Specification at page 4, lines 8-14. Sakashita does not teach or suggest that use of the titanium oxide powder having a diameter of 1  $\mu\text{m}$  or less is suitable for excellent dispersability in the binder resin and prevention of dropout of the solid lubricant from the film.

As discussed above, Sakashita does not teach or suggest the subject matter recited in independent claim 1. Therefore, claim 1 is allowable over Sakashita. Claims 3, 4, 7, 15-19 and 22 depend from claim 1 and are allowable for at least that reason. Applicants request that this ground of rejection be withdrawn.

**CONCLUSION**

Based on the foregoing amendments and remarks, Applicants respectfully request reconsideration and withdrawal of the rejection of claims and allowance of this application.

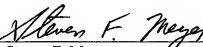
**AUTHORIZATION**

No fees are believed necessary in connection with this response. Should an additional extension of time be required, such extension is petitioned. The Commissioner is authorized to charge any other fees or credit any overpayments which may be required for this paper to Deposit Account Number **504827**, Order No. **1004378.51670**.

Respectfully submitted,  
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